

IN THE SPECIFICATION

Please amend the abstract at page 23, lines 2-5, as follows:

A contact $[(15)]$ and a copper interconnect line $[(16)]$ as an uppermost interconnect layer are buried in an interlayer insulating film $[(14)]$. A pad area $[(17)]$ including aluminum alloy (such as AlCu or AlSiCu) is buried in a predetermined area of the copper interconnect line $[(16)]$. A gold wire $[(18)]$ is bonded to the pad area $[(17)]$.